

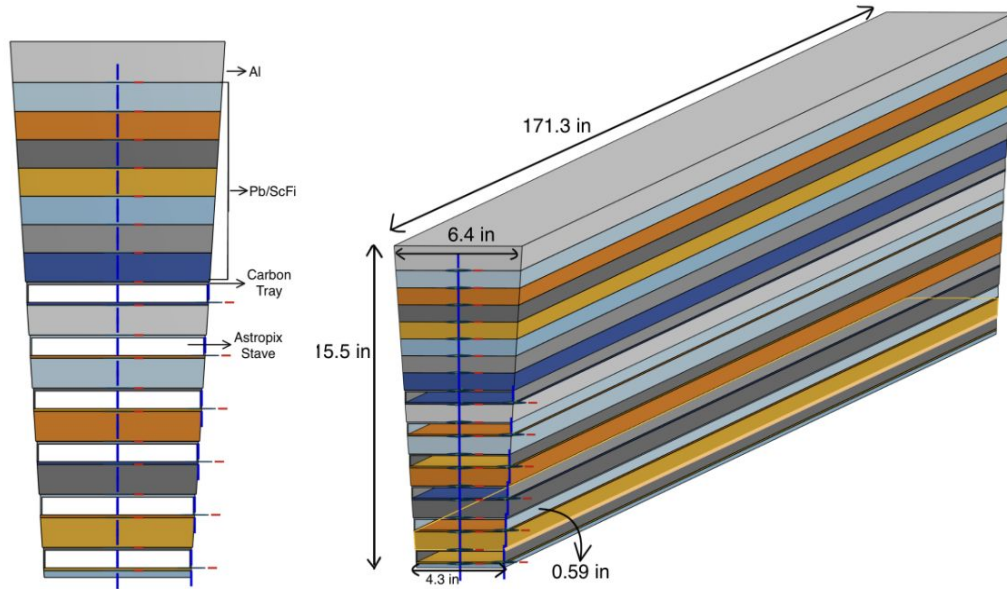
BIC full sector and ESB cooling

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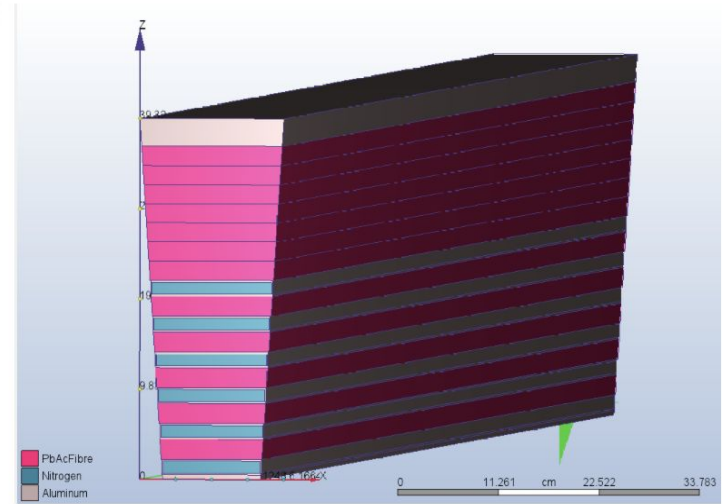
2025-05-13

A.) BIC full sector cooling

CAD model for complete sector

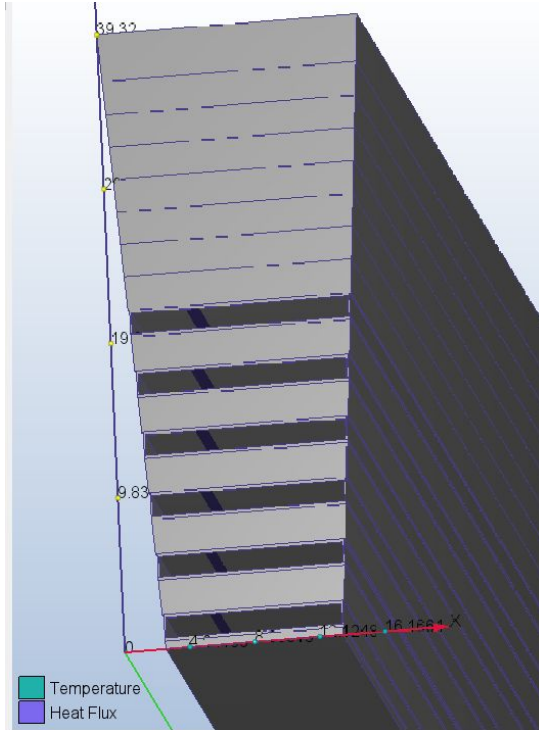


CAD Render of the sector

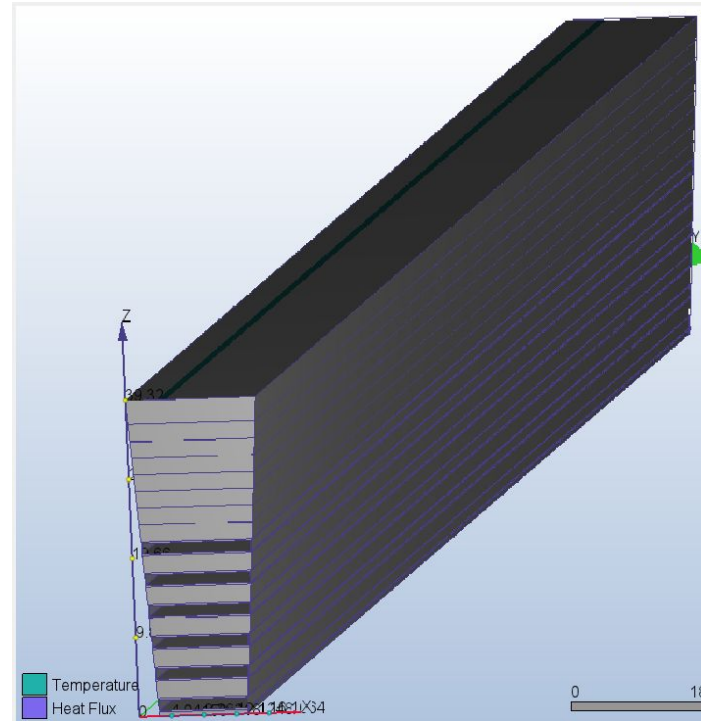


Material distribution

Boundary Conditions

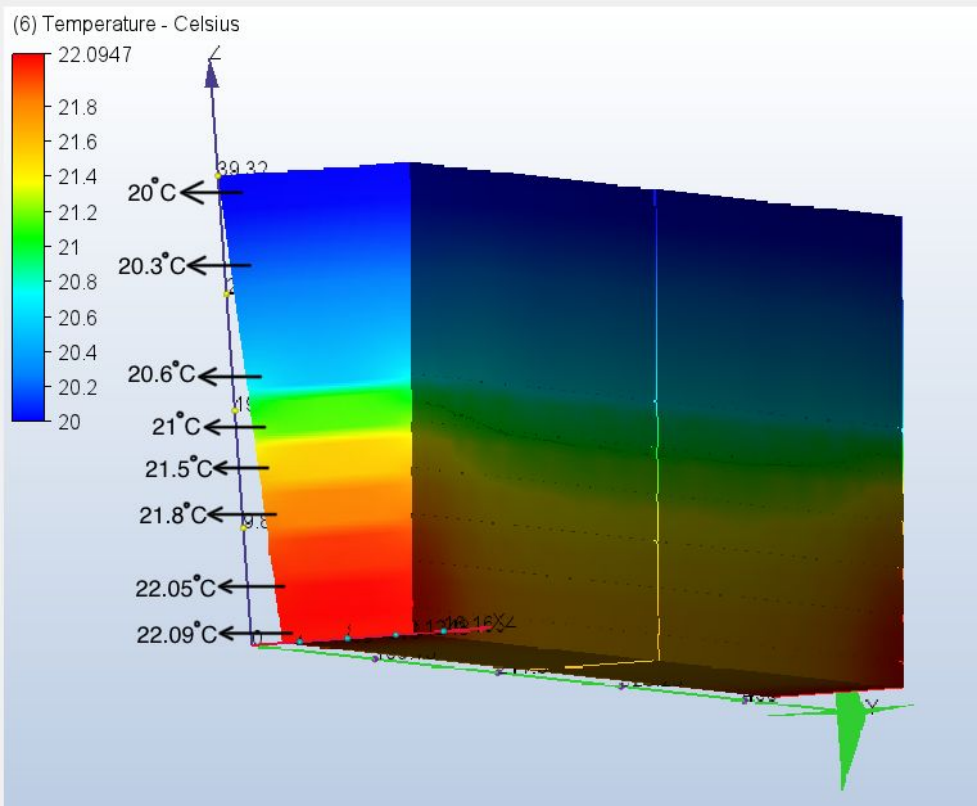


Boundary condition: Heat flux as 0.002 W/cm^2 on the top of the carbon tray.



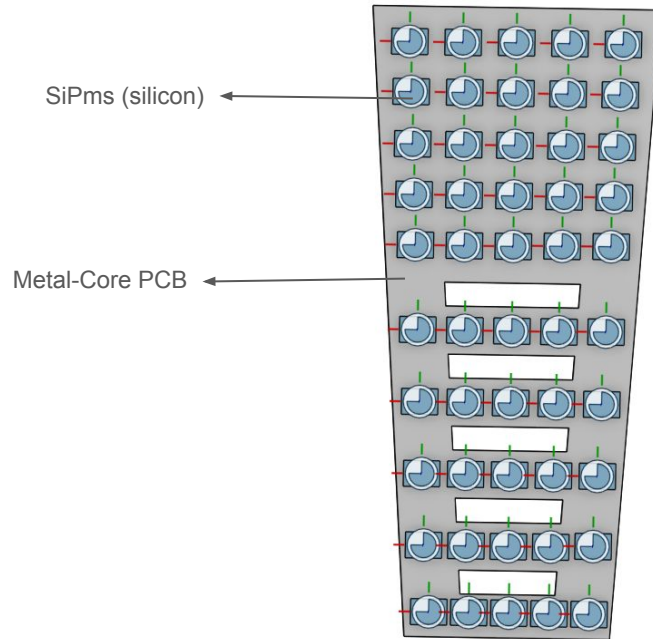
Boundary condition: Temperature as 20°C

Thermal Simulation

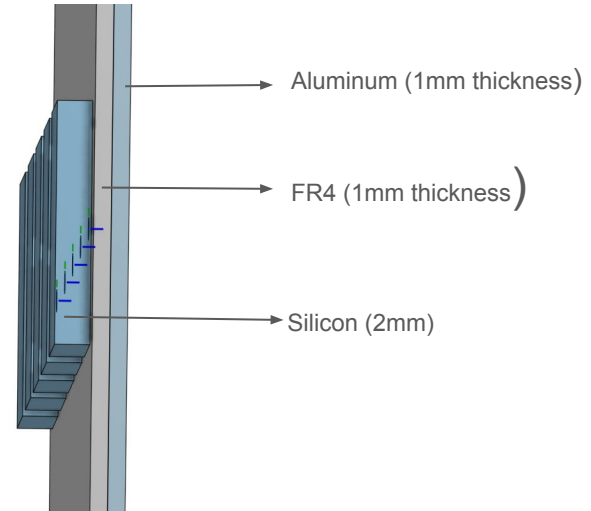


B.) BIC ESB cooling with metal core PCB

CAD Render

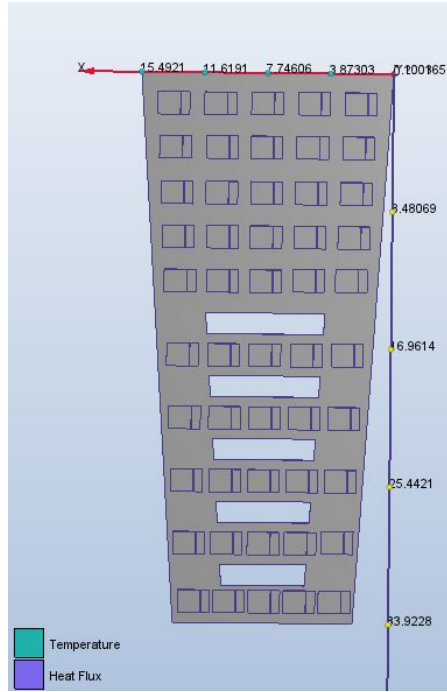


Front View of the board with SiPms

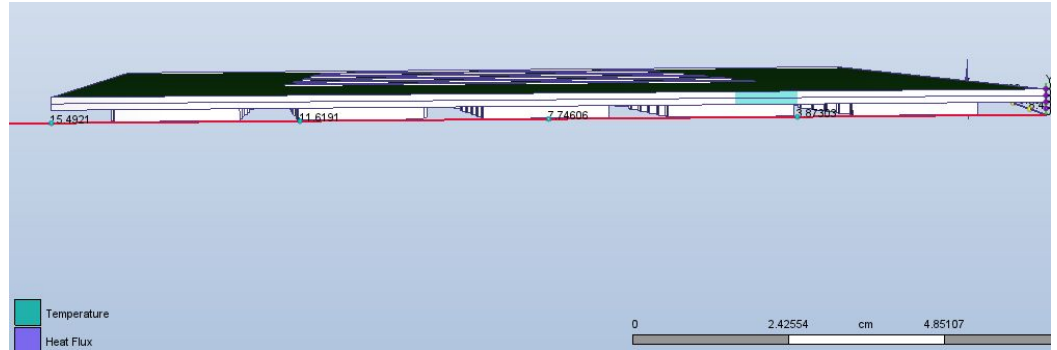


Side View of the Board

Boundary Conditions



Boundary Conditions on SiPms: Heat Flux as 0.056 W/cm^2 .



Boundary Condition on the top part of the Board and the Metal core: Temperature as 20°C .

Thermal Simulation

